

ABSTRACT OF THE DISCLOSURE
POLISHING AMOUNT CONTROL SYSTEM AND METHOD FOR SAME

5 A polishing amount control system and method for
same which can quickly feed back the results of
measurement of a coating layer of a workpiece to the
next polishing work so as to improve the productivity
of the workpieces and further enable high precision
polishing work. The thicknesses of the plating layers
10 of the two surfaces of a magnetic disk W polished by a
double-side polishing apparatus 1 are measured by an
X-ray thickness meter 2. The rotational speeds of the
drive motors 15 and 18 of the double-side polishing
apparatus 1 are controlled in accordance with the
15 results of the measurement. Specifically, the
polishing amounts of the plating layers of the upper
surface and lower surface of the magnetic disk W
polished next become within $1.8\ \mu\text{m}$ to $2.2\ \mu\text{m}$ by
controlling the rotational speeds of the upper platen
20 13 and the lower platen 11. The thickness difference
of the upper and lower surfaces of the same magnetic
disk W become within $-0.15\ \mu\text{m}$ to $+0.15\ \mu\text{m}$ by
controlling the rotational speed of one of the upper
platen 13 and lower platen 11.

Figure 1